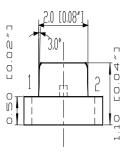
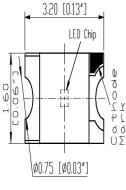
# 表面黏著型發光二極體指示燈

### S150 Series SMD Chip LED Lamps

Part Number: Q150YUS4

## Package outlines

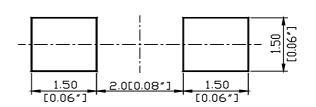








#### RECOMMEND PAD LAYOUT



ITEM	MATERIALS
Resin (mold)	Ероху
Bonding Wire	Ø <b>25</b> μm Au
Lens color	Water transparent
Printed circuit board	BT (white)
Dice	AlGaInP
Emitted color	Yellow

#### **NOTES:**

- 1. All dimensions are in millimeters (inches);
- 2. Tolerances are  $\pm 0.1$ mm (0.004inch) unless otherwise noted.

# 表面黏著型發光二極體指示燈

Part Number: Q150YUS4

Absolute maximum ratings	5	(T <sub>A</sub> =25°C)		
Parameter	Symbol	Value	Unit	
Forward current	lf	30	mA	
Reverse voltage	Vr	5	V	
Power dissipation	Pd	75	mW	
Operating temperature range	Тор	-20 ~+80	$^{\circ}$ C	
Storage temperature range	Tstg	-20 ~+80	$^{\circ}$ C	
Peak pulsing current (1/8 duty f=1kHz)	lfp	125	mA	
Electro-optical characteri	stics	$(T_{\lambda}=25^{\circ}C)$		

Electro-optical characteristics			(I <sub>A</sub> =25 C)			
Parameter	Test	Symbo	Value		Unit	
	Conditio	l l	Min	Тур	Max	
	n					
Wavelength at peak emission	lf=20mA	λpeak	590	595	600	nm
Spectral half bandwidth	If=20mA	Δλ		20		nm
Dominant wavelength	lf=20mA	λdom		590		nm
Forward voltage	lf=20mA	Vf		2.0	2.5	V
Luminous intensity *1	lf=20mA	lv		600		mcd
Viewing angle at 50% Iv	lf=10mA	201/2		140		Deg
Reverse current	Vr=5V	lr			10	μΑ

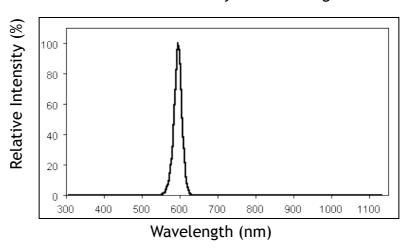
 $\pm\,1$  Note: Luminous intensity tolerance is  $\pm10^{\rm o}$  .

## 表面黏著型發光二極體指示燈

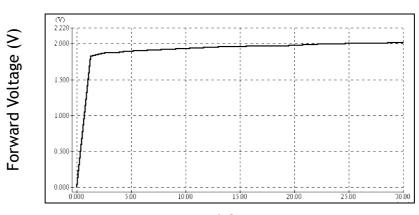
Part Number: Q150YUS4

## OPTICAL CHARACTERISTIC CURVES

#### Relative Intensity vs. Wavelength

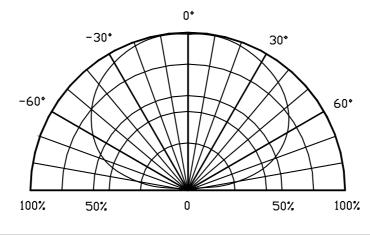


#### Forward Current vs. Forward Voltage



Forward Current (mA)

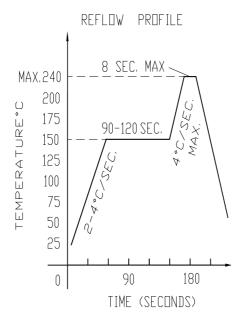
#### **Directive Characteristics**



## 表面黏著型發光二極體指示燈

### **Reflow Profile**

#### ■ Reflow Temp/Time

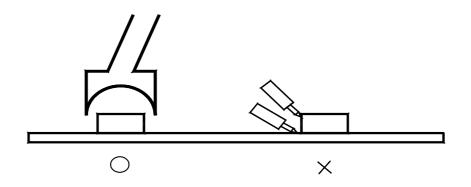


#### ■Soldering iron

Basic spec is  $\leq$  5sec when 260°C. If temperature is higher, time should be shorter

(+10°C  $\rightarrow$  -1sec ).Power dissipation of iron should be smaller than 15W, and temperatures should be controllable .Surface temperature of the device  $\blacksquare$ Rework

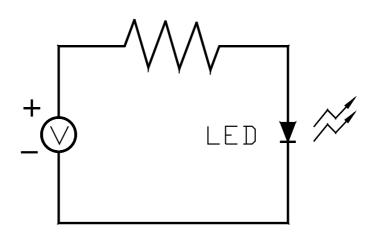
- 1. Customer must finish rework within 5 sec under 260°C.
- 2. The head of iron can not touch copper foil
- 3. Twin-head type is preferred.



## 表面黏著型發光二極體指示燈

### Test circuit and handling precautions

#### ■ Test circuit



#### ■ Handling precautions

1. Over-current-proof

Customer must apply resistors for protection; otherwise slight voltage shift will cause

big current change (Burn out will happen).

#### 2.Storage

2.1 It is recommended to store the products in the following conditions:

Humidity: 60% R.H. Max.

Temperature :  $5^{\circ}$ C ~  $30^{\circ}$ C ( $41^{\circ}$ F ~  $86^{\circ}$ F)

2.2 Shelf life in sealed bag: 12 month at <5%-30% and <30% R.H. after the package is

Opened, the products should be used within a week or they should be keeping to stored at

 $\leq$  20 R.H. with zip-lock sealed.

#### 3.Baking

It is recommended to baking before soldering when the pack is unsealed after 72hrs. The

Conditions are as followings:

- 3.1  $60\pm3$ °C x(12~24hrs) and <5%RH, taped reel type
- 3.2  $100\pm3$ °C x(45min~1hr), bulk type
- 3.3  $130\pm3^{\circ}$ C x(15~30min), bulk type

# 表面黏著型發光二極體指示燈

Test items and results of reliability							
Туре	Test Item	Test Conditions	Note	Number of Damaged			
Sequement A	Temperature Cycle	-20°C 30min ↑↓ 80°C 30min	100 cycle	0/22			
<b></b>	Thermal Shock	-20°C 15min ↑↓ 80°C 15min	100 cycle	0/22			
	High Humidity Heat Cycle	30°C⇔ 65°C 90%RH 24hrs/1cycle	10 cycle	0/22			
	High Temperature Storage	T <sub>a</sub> =80°C	1000 hrs	0/22			
	Humidity Heat Storage	T <sub>a</sub> =60°C RH=90%	1000 hrs	0/22			
ion	Low Temperature Storage	T <sub>a</sub> =-30°C	1000 hrs	0/22			
Se <b>openati</b> on	Life Test	$T_a$ =25 $^{\circ}$ C $I_F$ =20mA	1000 hrs	0/22			
	High Humidity Heat Life Test	60°C RH=90% I <sub>F</sub> =20mA	500 hrs	0/22			
	Low Temperature Life Test	T <sub>a</sub> =-20°C I <sub>F</sub> =20mA	1000 hrs	0/22			